

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	JUN '99	24325	9915 ATP (Anam, PI)	DK815282AAB	SOIC	50	45	0
DS1621	A7	SEP '99	24466	9930 ATP (Anam, PI)	DK906731AAC	SOIC	50	39	6
DS1869	A3	MAR '99	24025	9829 NSEB	DJ821534ABB	SOIC	25	50	0
DS1869	A3	JUN '99	24231	9836 NSEB	DJ824252AAC	SOIC	25	50	0
DS1869	A3	SEP '99	24445	9907 NSEB	DJ824247ABA	SOIC	25	46	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 217C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2502	C2	APR '99	23670	9845	Carsem	DM821484AA	TSOC	3	150	0
DS2502	C2	MAR '99	23636	9913	Carsem S	DM842206AL	SOIC	3	238	0
DS2502	C2	JUN '99	23958	9915	Carsem S	DM846764AA	SOIC	3	236	0
DS87C520	A14	NOV '99	24798	9931	ASI (Anam, K)	DN901118AAB	LCC	3	223	3

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C4	JAN '00	25055	9948	Carsem	DM925589AA	MQFP	3	201	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232L	C2	APR '99	23660	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	4	0
DS1232L	C2	JAN '00	25019	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	4	0
DS1233	A5	OCT '99	24563	9932	Carsem	DM924344AC	SOT223	4	0
DS1233	A5	JAN '00	25033	9952	Carsem	DM929359AB	SOT223	4	0
DS1267	A1	AUG '99	24340	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	4	0
DS1267	A1	FEB '99	23262	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	4	0
DS1267	A2	FEB '00	25172	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	4	0
DS1621	A7	JUN '99	24314	9915	ATP (Anam, PI)	DK815282AAB	SOIC	4	0
DS1621	A7	SEP '99	24459	9930	ATP (Anam, PI)	DK906731AAC	SOIC	4	0
DS174855	A4	AUG '99	24359	9906	ATP (Anam, PI)	DK838211AAF	SOIC	4	0
DS1803	A2	NOV '98	22797	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	4	0
DS1803	A2	FEB '99	23274	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	4	0
DS1803	A2	AUG '99	24367	9909	ATP (Anam, PI)	DK830515AAB	SOIC	4	0
DS1803	A2	NOV '99	24735	9923	ATP (Anam, PI)	DK913631AAA	SOIC	4	0
DS1869	A3	MAR '99	23360	9829	NSEB	DJ821534ABB	SOIC	4	0
DS1869	A3	JUN '99	23944	9836	NSEB	DJ824252AAC	SOIC	4	0
DS1869	A3	SEP '99	24438	9907	NSEB	DJ824247ABA	SOIC	4	0
DS2108	B7	AUG '99	24383	9922	ATP (Anam, PI)	DK913650AAF	SOIC	4	0
DS2108	B7	FEB '00	25103	9951	ASI (Anam, K)	DK940069AAC	SOIC	4	0
DS2109	A7	MAR '99	23363	9839	Carsem	DM812688AA	SOIC	4	0
DS2109	A7	JUN '99	23947	9839	Carsem	DM811523AA	SOIC	4	0
DS2109	A7	DEC '99	24805	9842	Carsem	DM812689AA	SOIC	4	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS2118M	A4	MAR '99	23365	9904	ASI (Anam, K)	DN844402AAC	SSOP	4	0
DS2118M	A4	JUN '99	23949	9912	ASI (Anam, K)	DN848138AAA	SSOP	4	0
DS2118M	A4	SEP '99	24450	9919	Carsem	DM905555AA	SSOP	4	0
DS2153	A7	MAR '99	23367	9901	ASI (Anam, K)	DN819185AAB	LCC	4	0
DS2154	A2	JUN '99	23951	9914	ASI (Anam, K)	DN901043AAC	LQFP	4	0
DS2165	B1	OCT '98	22680	9837	ASI (Anam, K)	DN811583AAB	LCC	4	0
DS2180	B3	APR '99	23667	9850	ASI (Anam, K)	DN839402AAC	LCC	4	0
DS21S07A	B3	FEB '99	23276	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	4	0
DS21S07A	F	NOV '99	24727	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	4	0
DS21S07A	F	AUG '99	24375	9913	Carsem S	DM828145AA	TSSOP	4	0
DS21S07A	F	FEB '00	25095	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	4	0
DS2502	C2	APR '99	23669	9845	Carsem	DM821484AA	TSOC	4	0
DS2502	C2	MAR '99	23635	9913	Carsem S	DM842206AL	SOIC	4	0
DS2502	C2	JUN '99	23957	9915	Carsem S	DM846764AA	SOIC	4	0
DS5002	C4	OCT '99	24576	9931	Carsem	DM849386AA	MQFP	4	0
DS5002	C4	JAN '00	25054	9948	Carsem	DM925589AA	MQFP	4	0
DS87C520	A11	AUG '99	24402	9922	ASI (Anam, K)	DN850735AAB	LCC	4	0
DS87C520	A14	NOV '99	24797	9931	ASI (Anam, K)	DN901118AAB	LCC	4	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY			LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY	POINT			QTY	FAIL	
DS1000	E3	OCT '99	24793	9944	CPS (ChipPac, China)	DH927108AJC	DIP	300	40	0	
DS1000	E3	OCT '99	24793	9944	CPS (ChipPac, China)	DH927108AJC	DIP	1000	40	0	
DS1232L	C2	APR '99	24191	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	300	39	0	
DS1232L	C2	APR '99	24191	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	1000	39	0	
DS1233	A5	OCT '99	24568	9932	Carsem	DM924344AC	SOT223	300	40	0	
DS1233	A5	OCT '99	24568	9932	Carsem	DM924344AC	SOT223	1000	40	0	
DS1267	A1	FEB '99	24133	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	300	40	0	
DS1267	A1	AUG '99	24345	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	300	40	0	
DS1267	A1	FEB '99	24133	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	700	40	0	
DS1267	A1	AUG '99	24345	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	1000	40	0	
DS1302	A3	JUN '99	24514	9905	ATP (Anam, PI)	DK824165AAA	DIP	300	40	0	
DS1302	A3	JUN '99	24514	9905	ATP (Anam, PI)	DK824165AAA	DIP	1000	39	1	
DS1621	A7	JUN '99	24323	9915	ATP (Anam, PI)	DK815282AAB	SOIC	300	40	0	
DS1621	A7	JUN '99	24323	9915	ATP (Anam, PI)	DK815282AAB	SOIC	1000	40	0	
DS1621	A7	SEP '99	24464	9930	ATP (Anam, PI)	DK906731AAC	SOIC	300	36	0	
DS1621	A7	SEP '99	24464	9930	ATP (Anam, PI)	DK906731AAC	SOIC	1000	36	0	
DS174855	A4	AUG '99	24364	9906	ATP (Anam, PI)	DK838211AAF	SOIC	300	50	0	
DS1803	A2	NOV '98	23924	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	300	40	0	
DS1803	A2	NOV '98	23924	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	1000	40	0	
DS1803	A2	FEB '99	24004	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	300	40	0	
DS1803	A2	FEB '99	24004	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	1000	40	0	
DS1803	A2	AUG '99	24372	9909	ATP (Anam, PI)	DK830515AAB	SOIC	300	39	0	

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1803	A2	NOV '99	24740	9923	ATP (Anam, PI)	DK913631AAA	SOIC	300	40	0
DS1869	A3	MAR '99	24023	9829	NSEB	DJ821534ABB	SOIC	300	40	0
DS1869	A3	MAR '99	24023	9829	NSEB	DJ821534ABB	SOIC	1000	40	0
DS1869	A3	JUN '99	24229	9836	NSEB	DJ824252AAC	SOIC	300	39	0
DS1869	A3	JUN '99	24229	9836	NSEB	DJ824252AAC	SOIC	1000	39	0
DS1869	A3	SEP '99	24443	9907	NSEB	DJ824247ABA	SOIC	300	35	0
DS1869	A3	SEP '99	24443	9907	NSEB	DJ824247ABA	SOIC	1000	35	0
DS2108	B7	AUG '99	24388	9922	ATP (Anam, PI)	DK913650AAF	SOIC	300	40	0
DS2108	B7	AUG '99	24388	9922	ATP (Anam, PI)	DK913650AAF	SOIC	1000	40	0
DS2109	A7	MAR '99	23833	9839	Carsem	DM812688AA	SOIC	300	50	0
DS2109	A7	MAR '99	23833	9839	Carsem	DM812688AA	SOIC	1000	50	0
DS2118M	A4	MAR '99	23601	9904	ASI (Anam, K)	DN844402AAC	SSOP	300	40	0
DS2118M	A4	MAR '99	23601	9904	ASI (Anam, K)	DN844402AAC	SSOP	1000	40	0
DS2118M	A4	JUN '99	24071	9912	ASI (Anam, K)	DN848138AAA	SSOP	300	40	0
DS2118M	A4	JUN '99	24071	9912	ASI (Anam, K)	DN848138AAA	SSOP	1000	40	0
DS2118M	A4	SEP '99	24455	9919	Carsem	DM905555AA	SSOP	300	39	0
DS2118M	A4	SEP '99	24455	9919	Carsem	DM905555AA	SSOP	1000	39	0
DS2154	A2	JUN '99	24428	9914	ASI (Anam, K)	DN901043AAC	LQFP	300	40	0
DS2154	A2	JUN '99	24428	9914	ASI (Anam, K)	DN901043AAC	LQFP	1000	40	0
DS2165	B1	OCT '98	23169	9837	ASI (Anam, K)	DN811583AAB	LCC	300	60	0
DS2165	B1	OCT '98	23169	9837	ASI (Anam, K)	DN811583AAB	LCC	1000	60	0
DS2180	B3	APR '99	23880	9850	ASI (Anam, K)	DN839402AAC	LCC	300	60	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2180	B3	APR '99	23880	9850	ASI (Anam, K)	DN839402AAC	LCC	1000	60	0
DS21S07A	B3	FEB '99	24211	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	300	35	0
DS21S07A	B3	FEB '99	24211	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	1000	35	0
DS21S07A	F	NOV '99	24732	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	300	40	0
DS21S07A	F	NOV '99	24732	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	1000	40	0
DS21S07A	F	AUG '99	24380	9913	Carsem S	DM828145AA	TSSOP	300	38	0
DS21S07A	F	AUG '99	24380	9913	Carsem S	DM828145AA	TSSOP	1000	38	0
DS2401	C2	DEC '99	24815	9943	Carsem	DM920572AA	TO92	300	40	0
DS2401	C2	DEC '99	24815	9943	Carsem	DM920572AA	TO92	1000	40	0
DS2434	D1	NOV '99	24714	9851	Carsem	DM833262AA	TO226 (PR35)	300	50	0
DS2434	D1	NOV '99	24714	9851	Carsem	DM833262AA	TO226 (PR35)	1000	50	0
DS2502	C2	APR '99	24266	9845	Carsem	DM821484AA	TSOC	300	77	0
DS2502	C2	APR '99	24266	9845	Carsem	DM821484AA	TSOC	1000	75	0
DS2502	C2	MAR '99	24262	9913	Carsem S	DM842206AL	SOIC	300	34	0
DS2502	C2	MAR '99	24262	9913	Carsem S	DM842206AL	SOIC	1000	34	0
DS2502	C2	JUN '99	24175	9915	Carsem S	DM846764AA	SOIC	300	40	0
DS2502	C2	JUN '99	24175	9915	Carsem S	DM846764AA	SOIC	1000	40	0
DS2502	C3	JAN '00	25052	9930	CPS (ChipPac, China)	DH917304BAA	TSOC	300	77	0
DS80C320	C5	OCT '99	24586	9938	CPS (ChipPac, China)	DH925592AAB	DIP	300	40	0
DS80C320	C5	OCT '99	24586	9938	CPS (ChipPac, China)	DH925592AAB	DIP	1000	40	0
DS87C520	A11	AUG '99	24407	9922	ASI (Anam, K)	DN850735AAB	LCC	300	40	0
DS87C520	A11	AUG '99	24407	9922	ASI (Anam, K)	DN850735AAB	LCC	1000	40	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230Y	A1	JAN '99	23060	9844	Dallas	105760	Low Profile Module	300	77	0
DS1230Y	A1	JAN '99	23060	9844	Dallas	105760	Low Profile Module	1000	77	0
DS1230Y	B1	APR '99	23658	9908	Dallas	104242	Low Profile Module	300	77	0
DS1230Y	B1	APR '99	23658	9908	Dallas	104242	Low Profile Module	1000	77	0
DS1230Y	B1	OCT '99	24557	9921	Dallas	108803	Module w/SMT	300	100	0
DS1230Y	B1	OCT '99	24557	9921	Dallas	108803	Module w/SMT	1000	100	0
DS1230Y	B1	OCT '99	24561	9939	Dallas	109958	Low Profile Module	300	77	0
DS12887	A2	OCT '99	24574	9933	Fastech	111248-SP1	Module w/Bent Fra	300	100	0
DS12887	A2	OCT '99	24574	9933	Fastech	111248-SP1	Module w/Bent Fra	1000	100	0
DS1643	B2	FEB '99	23272	9905	Dallas	107121	Module w/Hi Densit	300	77	0
DS1643	B2	FEB '99	23272	9905	Dallas	107121	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	300	77	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	1000	74	3
DS1643	C1	NOV '99	24725	9939	Dallas	113476	Module w/Hi Densit	300	77	0
DS1643	C1	NOV '99	24725	9939	Dallas	113476	Module w/Hi Densit	1000	77	0
DS1991	E8	SEP '99	24470	9925	Dallas	DS838190AA-	Tch Can F50	300	77	0
DS1991	E8	SEP '99	24470	9925	Dallas	DS838190AA-	Tch Can F50	1000	77	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1621	A7	JUN '99	24326	9915	ATP (Anam, PI)	DK815282AAB	SOIC	336	44	1
DS1621	A7	JUN '99	24326	9915	ATP (Anam, PI)	DK815282AAB	SOIC	1000	44	0
DS1621	A7	SEP '99	24467	9930	ATP (Anam, PI)	DK906731AAC	SOIC	336	39	0
DS1621	A7	SEP '99	24467	9930	ATP (Anam, PI)	DK906731AAC	SOIC	1000	38	1
DS1869	A3	MAR '99	24288	9829	NSEB	DJ821534ABB	SOIC	336	46	0
DS1869	A3	MAR '99	24288	9829	NSEB	DJ821534ABB	SOIC	1000	45	0
DS1869	A3	JUN '99	24252	9836	NSEB	DJ824252AAC	SOIC	336	50	0
DS1869	A3	JUN '99	24252	9836	NSEB	DJ824252AAC	SOIC	1000	50	0
DS1869	A3	SEP '99	24446	9907	NSEB	DJ824247ABA	SOIC	336	46	0
DS1869	A3	SEP '99	24446	9907	NSEB	DJ824247ABA	SOIC	1000	46	0
DS2502	C2	MAR '99	24264	9913	Carsem S	DM842206AL	SOIC	336	34	0
DS2502	C2	MAR '99	24264	9913	Carsem S	DM842206AL	SOIC	1000	34	0
DS2502	C2	JUN '99	24177	9915	Carsem S	DM846764AA	SOIC	336	37	0
DS2502	C2	JUN '99	24177	9915	Carsem S	DM846764AA	SOIC	1000	37	0
DS87C520	A11	AUG '99	24409	9922	ASI (Anam, K)	DN850735AAB	LCC	336	51	0
DS87C520	A11	AUG '99	24409	9922	ASI (Anam, K)	DN850735AAB	LCC	1000	51	0
DS87C520	A14	NOV '99	24804	9931	ASI (Anam, K)	DN901118AAB	LCC	336	40	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230Y	A1	JAN '99	23059	9844	Dallas	105760	Low Profile Module	336	77	0
DS1230Y	A1	JAN '99	23059	9844	Dallas	105760	Low Profile Module	1000	77	0
DS1230Y	B1	APR '99	23657	9908	Dallas	104242	Low Profile Module	336	77	0
DS1230Y	B1	APR '99	23657	9908	Dallas	104242	Low Profile Module	1000	77	0
DS1230Y	B1	OCT '99	24560	9939	Dallas	109958	Low Profile Module	336	77	0
DS1230Y	B1	OCT '99	24560	9939	Dallas	109958	Low Profile Module	1000	77	0
DS1230Y	B1	JAN '00	25011	9944	Dallas	110596	Low Profile Module	336	77	0
DS1230Y	B1	JAN '00	25011	9944	Dallas	110596	Low Profile Module	1000	77	0
DS1386	A1	NOV '99	24718	9943	Dallas	11419	Power Cap	336	77	0
DS1643	B2	FEB '99	23271	9905	Dallas	107121	Module w/Hi Densit	336	77	0
DS1643	B2	FEB '99	23271	9905	Dallas	107121	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	336	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	1000	77	0
DS1643	C1	NOV '99	24724	9939	Dallas	113476	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '99	24724	9939	Dallas	113476	Module w/Hi Densit	1000	77	0
DS1991	E8	SEP '99	24469	9925	Dallas	DS838190AA-	Tch Can F50	336	76	0
DS1991	E8	SEP '99	24469	9925	Dallas	DS838190AA-	Tch Can F50	1000	76	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230A	B1	JAN '00	25007	9952 Fastech	114146	Module w/SMT	48	200	0
DS1230Y	B1	OCT '99	24556	9921 Dallas	108803	Module w/SMT	48	200	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230A	B1	JAN '00	25005	9952	Fastech	114146	Module w/SMT	3	0
DS1230Y	B1	OCT '99	24554	9921	Dallas	108803	Module w/SMT	3	0
DS12887	A2	OCT '99	24571	9933	Fastech	111248-SP1	Module w/Bent Fra	3	0
DS12887	A2	JAN '00	25028	9950	Fastech	115426	Module w/Bent Fra	3	0
DS1643	B2	FEB '99	23269	9905	Dallas	107121	Module w/Hi Densit	3	0
DS1643	C1	AUG '99	24348	9929	Dallas	111344	Module w/Hi Densit	3	0
DS1643	C1	NOV '99	24722	9939	Dallas	113476	Module w/Hi Densit	3	0

RELIABILITY MONITOR

STRESS: SOLDER HEAT

CONDITIONS: HTC VAPOR PHASE

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1267	A1	FEB '99	23263	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	3	233	0
DS1803	A2	NOV '98	22798	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	3	238	0
DS1803	A2	FEB '99	23275	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	3	238	0
DS1869	A3	MAR '99	23361	9829	NSEB	DJ821534ABB	SOIC	3	241	0
DS1869	A3	JUN '99	23945	9836	NSEB	DJ824252AAC	SOIC	3	234	0
DS2153	A7	MAR '99	23368	9901	ASI (Anam, K)	DN819185AAB	LCC	3	241	0
DS2165	B1	OCT '98	22681	9837	ASI (Anam, K)	DN811583AAB	LCC	3	240	0
DS2180	B3	APR '99	23668	9850	ASI (Anam, K)	DN839402AAC	LCC	3	241	0
DS87C520	A11	AUG '99	24403	9922	ASI (Anam, K)	DN850735AAB	LCC	3	228	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					POINT	QTY FAIL
DS1232L	C2	APR '99	24188	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	4	0
DS1233	A5	OCT '99	24565	9932	Carsem	DM924344AC	SOT223	4	0
DS1233	A5	JAN '00	25035	9952	Carsem	DM929359AB	SOT223	4	0
DS1267	A1	AUG '99	24342	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	4	0
DS1267	A1	FEB '99	24043	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	4	0
DS1621	A7	JUN '99	24316	9915	ATP (Anam, PI)	DK815282AAB	SOIC	4	0
DS1621	A7	SEP '99	24461	9930	ATP (Anam, PI)	DK906731AAC	SOIC	4	0
DS174855	A4	AUG '99	24361	9906	ATP (Anam, PI)	DK838211AAF	SOIC	4	0
DS1803	A2	NOV '98	23172	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	4	0
DS1803	A2	FEB '99	23927	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	4	0
DS1803	A2	AUG '99	24369	9909	ATP (Anam, PI)	DK830515AAB	SOIC	4	0
DS1803	A2	NOV '99	24737	9923	ATP (Anam, PI)	DK913631AAA	SOIC	4	0
DS1869	A3	MAR '99	23439	9829	NSEB	DJ821534ABB	SOIC	4	0
DS1869	A3	JUN '99	24031	9836	NSEB	DJ824252AAC	SOIC	4	0
DS1869	A3	SEP '99	24440	9907	NSEB	DJ824247ABA	SOIC	4	0
DS2108	B7	AUG '99	24385	9922	ATP (Anam, PI)	DK913650AAF	SOIC	4	0
DS2108	B7	FEB '00	25105	9951	ASI (Anam, K)	DK940069AAC	SOIC	4	0
DS2109	A7	MAR '99	23722	9839	Carsem	DM812688AA	SOIC	4	0
DS2109	A7	DEC '99	24807	9842	Carsem	DM812689AA	SOIC	3	1
DS2118M	A4	MAR '99	23525	9904	ASI (Anam, K)	DN844402AAC	SSOP	4	0
DS2118M	A4	JUN '99	24037	9912	ASI (Anam, K)	DN848138AAA	SSOP	4	0
DS2118M	A4	SEP '99	24452	9919	Carsem	DM905555AA	SSOP	4	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					POINT	QTY FAIL
DS2153	A7	MAR '99	23621	9901	ASI (Anam, K)	DN819185AAB	LCC	4	0
DS2154	A2	JUN '99	24425	9914	ASI (Anam, K)	DN901043AAC	LQFP	4	0
DS2165	B1	OCT '98	22756	9837	ASI (Anam, K)	DN811583AAB	LCC	4	0
DS2180	B3	APR '99	23774	9850	ASI (Anam, K)	DN839402AAC	LCC	4	0
DS21S07A	B3	FEB '99	24208	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	4	0
DS21S07A	F	NOV '99	24729	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	4	0
DS21S07A	F	AUG '99	24377	9913	Carsem S	DM828145AA	TSSOP	4	0
DS21S07A	F	FEB '00	25097	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	4	0
DS2502	C2	APR '99	24265	9845	Carsem	DM821484AA	TSOC	4	0
DS2502	C2	MAR '99	24152	9913	Carsem S	DM842206AL	SOIC	4	0
DS2502	C2	JUN '99	24168	9915	Carsem S	DM846764AA	SOIC	4	0
DS2502	C3	JAN '00	25051	9930	CPS (ChipPac, China)	DH917304BAA	TSOC	4	0
DS5002	C4	OCT '99	24578	9931	Carsem	DM849386AA	MQFP	4	0
DS5002	C4	JAN '00	25056	9948	Carsem	DM925589AA	MQFP	4	0
DS87C520	A11	AUG '99	24404	9922	ASI (Anam, K)	DN850735AAB	LCC	4	0
DS87C520	A14	NOV '99	24799	9931	ASI (Anam, K)	DN901118AAB	LCC	4	0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230A	B1	JAN '00	25006	9952 Fastech	114146	Module w/SMT	6 0
DS1230Y	A1	JAN '99	23058	9844 Dallas	105760	Low Profile Module	6 0
DS1230Y	B1	APR '99	23656	9908 Dallas	104242	Low Profile Module	6 0
DS1230Y	B1	OCT '99	24555	9921 Dallas	108803	Module w/SMT	6 0
DS1230Y	B1	OCT '99	24559	9939 Dallas	109958	Low Profile Module	6 0
DS1230Y	B1	JAN '00	25010	9944 Dallas	110596	Low Profile Module	6 0
DS12887	A2	OCT '99	24572	9933 Fastech	111248-SP1	Module w/Bent Fra	6 0
DS12887	A2	JAN '00	25029	9950 Fastech	115426	Module w/Bent Fra	6 0
DS1386	A1	NOV '99	24717	9943 Dallas	11419	Power Cap	6 0
DS1643	B2	FEB '99	23270	9905 Dallas	107121	Module w/Hi Densit	6 0
DS1643	C1	AUG '99	24349	9929 Dallas	111344	Module w/Hi Densit	6 0
DS1643	C1	NOV '99	24723	9939 Dallas	113476	Module w/Hi Densit	6 0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230A	B1	JAN '00	25009	9952	Fastech	114146	Module w/SMT	288	100	0
DS1230Y	A1	JAN '99	23061	9844	Dallas	105760	Low Profile Module	288	77	0
DS1230Y	A1	JAN '99	23061	9844	Dallas	105760	Low Profile Module	960	75	2
DS1230Y	B1	APR '99	23659	9908	Dallas	104242	Low Profile Module	288	77	0
DS1230Y	B1	APR '99	23659	9908	Dallas	104242	Low Profile Module	960	77	0
DS1230Y	B1	OCT '99	24558	9921	Dallas	108803	Module w/SMT	288	100	0
DS1230Y	B1	OCT '99	24558	9921	Dallas	108803	Module w/SMT	960	100	0
DS1230Y	B1	OCT '99	24562	9939	Dallas	109958	Low Profile Module	288	77	0
DS1230Y	B1	OCT '99	24562	9939	Dallas	109958	Low Profile Module	960	77	0
DS1230Y	B1	JAN '00	25013	9944	Dallas	110596	Low Profile Module	288	77	0
DS1643	B2	FEB '99	23273	9905	Dallas	107121	Module w/Hi Densit	288	73	4
DS1643	B2	FEB '99	23273	9905	Dallas	107121	Module w/Hi Densit	960	60	13
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	288	77	0
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	960	76	1
DS1643	C1	NOV '99	24726	9939	Dallas	113476	Module w/Hi Densit	288	77	0
DS1643	C1	NOV '99	24726	9939	Dallas	113476	Module w/Hi Densit	960	77	0

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2	OCT '99	24573	9933 Fastech	111248-SP1	Module w/Bent Fra	48	200	0
DS12887	A2	JAN '00	25030	9950 Fastech	115426	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	JUN '99	24430	9914 ASI (Anam, K)	DN901043AAC	LQFP	100	48	0

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232L	C2	APR '99	24192	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	100	77	0
DS1233	A5	OCT '99	24569	9932	Carsem	DM924344AC	SOT223	100	71	0
DS2109	A7	MAR '99	23834	9839	Carsem	DM812688AA	SOIC	100	66	0
DS2118M	A4	MAR '99	23602	9904	ASI (Anam, K)	DN844402AAC	SSOP	100	76	0
DS2118M	A4	JUN '99	24072	9912	ASI (Anam, K)	DN848138AAA	SSOP	100	77	0
DS2118M	A4	SEP '99	24456	9919	Carsem	DM905555AA	SSOP	100	77	0
DS2154	A2	JUN '99	24429	9914	ASI (Anam, K)	DN901043AAC	LQFP	100	9	0
DS2165	B1	OCT '98	23170	9837	ASI (Anam, K)	DN811583AAB	LCC	100	60	0
DS2180	B3	APR '99	23881	9850	ASI (Anam, K)	DN839402AAC	LCC	100	60	0
DS2401	C2	DEC '99	24816	9943	Carsem	DM920572AA	TO92	100	74	0
DS2434	D1	NOV '99	24715	9851	Carsem	DM833262AA	TO226 (PR35)	100	70	0
DS87C520	A11	AUG '99	24408	9922	ASI (Anam, K)	DN850735AAB	LCC	100	55	0

RELIABILITY MONITOR

STRESS: EXTERNAL VISUAL

CONDITIONS: MIL-STD-883-2009

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	JUN '99	24425	9914	ASI (Anam, K)	DN901043AAC	LQFP		4	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C4	OCT '99	24577	9931 Carsem	DM849386AA	MQFP	3	195	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232L	C2	APR '99	23661	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	3	238	0
DS1233	A5	OCT '99	24564	9932	Carsem	DM924344AC	SOT223	3	233	0
DS1233	A5	JAN '00	25034	9952	Carsem	DM929359AB	SOT223	3	233	0
DS1267	A1	AUG '99	24341	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	3	232	0
DS1621	A7	JUN '99	24315	9915	ATP (Anam, PI)	DK815282AAB	SOIC	3	241	0
DS1621	A7	SEP '99	24460	9930	ATP (Anam, PI)	DK906731AAC	SOIC	3	240	0
DS174855	A4	AUG '99	24360	9906	ATP (Anam, PI)	DK838211AAF	SOIC	3	235	0
DS1803	A2	AUG '99	24368	9909	ATP (Anam, PI)	DK830515AAB	SOIC	3	238	0
DS1803	A2	NOV '99	24736	9923	ATP (Anam, PI)	DK913631AAA	SOIC	3	228	0
DS1869	A3	SEP '99	24439	9907	NSEB	DJ824247ABA	SOIC	3	235	0
DS2108	B7	AUG '99	24384	9922	ATP (Anam, PI)	DK913650AAF	SOIC	3	238	0
DS2108	B7	FEB '00	25104	9951	ASI (Anam, K)	DK940069AAC	SOIC	3	238	0
DS2109	A7	JUN '99	23948	9839	Carsem	DM811523AA	SOIC	3	237	0
DS2109	A7	MAR '99	23364	9839	Carsem	DM812688AA	SOIC	3	237	0
DS2109	A7	DEC '99	24806	9842	Carsem	DM812689AA	SOIC	3	236	0
DS2118M	A4	MAR '99	23366	9904	ASI (Anam, K)	DN844402AAC	SSOP	3	238	0
DS2118M	A4	JUN '99	23950	9912	ASI (Anam, K)	DN848138AAA	SSOP	3	238	0
DS2118M	A4	SEP '99	24451	9919	Carsem	DM905555AA	SSOP	3	236	0
DS2154	A2	JUN '99	23952	9914	ASI (Anam, K)	DN901043AAC	LQFP	3	235	0
DS21S07A	B3	FEB '99	23277	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	3	238	0
DS21S07A	F	NOV '99	24728	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	3	235	0
DS21S07A	F	AUG '99	24376	9913	Carsem S	DM828145AA	TSSOP	3	238	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21S07A	F	FEB '00	25096	9937 ATP (Anam, PI)	DK926747AAP	TSSOP	3	238	0
DS2502	C3	JAN '00	25050	9930 CPS (ChipPac, China)	DH917304BAA	TSOC	3	147	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '99	24794	9944	CPS (ChipPac, China)	DH927108AJC	DIP	274	77	0
DS1000	E3	OCT '99	24794	9944	CPS (ChipPac, China)	DH927108AJC	DIP	959	77	0
DS1267	A1	AUG '99	24346	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	274	77	0
DS1267	A1	FEB '99	24134	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	274	75	0
DS1267	A1	FEB '99	24134	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	959	73	0
DS12887	A2	OCT '99	24575	9933	Fastech	111248-SP1	Module w/Bent Fra	274	95	0
DS12887	A2	OCT '99	24575	9933	Fastech	111248-SP1	Module w/Bent Fra	959	95	0
DS12887	A2	JAN '00	25032	9950	Fastech	115426	Module w/Bent Fra	274	100	0
DS1302	A3	JUN '99	24515	9905	ATP (Anam, PI)	DK824165AAA	DIP	274	75	0
DS1302	A3	JUN '99	24515	9905	ATP (Anam, PI)	DK824165AAA	DIP	959	75	0
DS1621	A7	JUN '99	24324	9915	ATP (Anam, PI)	DK815282AAB	SOIC	274	69	0
DS1621	A7	JUN '99	24324	9915	ATP (Anam, PI)	DK815282AAB	SOIC	959	69	0
DS1621	A7	SEP '99	24465	9930	ATP (Anam, PI)	DK906731AAC	SOIC	274	63	0
DS1621	A7	SEP '99	24465	9930	ATP (Anam, PI)	DK906731AAC	SOIC	959	62	0
DS1803	A2	NOV '98	23925	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	274	77	0
DS1803	A2	FEB '99	24005	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	274	77	0
DS1803	A2	AUG '99	24373	9909	ATP (Anam, PI)	DK830515AAB	SOIC	274	77	0
DS1803	A2	NOV '99	24741	9923	ATP (Anam, PI)	DK913631AAA	SOIC	274	67	0
DS1869	A3	MAR '99	24024	9829	NSEB	DJ821534ABB	SOIC	274	70	0
DS1869	A3	MAR '99	24024	9829	NSEB	DJ821534ABB	SOIC	959	65	0
DS1869	A3	JUN '99	24230	9836	NSEB	DJ824252AAC	SOIC	274	63	0
DS1869	A3	JUN '99	24230	9836	NSEB	DJ824252AAC	SOIC	959	61	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1869	A3	SEP '99	24444	9907	NSEB	DJ824247ABA	SOIC	274	53	0
DS1869	A3	SEP '99	24444	9907	NSEB	DJ824247ABA	SOIC	959	53	0
DS2108	B7	AUG '99	24389	9922	ATP (Anam, PI)	DK913650AAF	SOIC	274	77	0
DS2108	B7	AUG '99	24389	9922	ATP (Anam, PI)	DK913650AAF	SOIC	959	77	0
DS21S07A	B3	FEB '99	24212	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	274	76	0
DS21S07A	B3	FEB '99	24212	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	959	63	0
DS21S07A	F	NOV '99	24733	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	274	73	0
DS21S07A	F	NOV '99	24733	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	959	73	0
DS21S07A	F	AUG '99	24381	9913	Carsem S	DM828145AA	TSSOP	274	70	0
DS21S07A	F	AUG '99	24381	9913	Carsem S	DM828145AA	TSSOP	959	70	0
DS2502	C2	MAR '99	24263	9913	Carsem S	DM842206AL	SOIC	274	76	0
DS2502	C2	MAR '99	24263	9913	Carsem S	DM842206AL	SOIC	959	74	0
DS2502	C2	JUN '99	24176	9915	Carsem S	DM846764AA	SOIC	274	75	0
DS2502	C2	JUN '99	24176	9915	Carsem S	DM846764AA	SOIC	959	75	0
DS80C320	C5	OCT '99	24587	9938	CPS (ChipPac, China)	DH925592AAB	DIP	274	77	0
DS80C320	C5	OCT '99	24587	9938	CPS (ChipPac, China)	DH925592AAB	DIP	959	77	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C STEAM, UNBIASED

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '99	24795	9944	CPS (ChipPac, China)	DH927108AJC	DIP	96	37	0
DS1232L	C2	APR '99	24193	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	96	36	0
DS1233	A5	OCT '99	24570	9932	Carsem	DM924344AC	SOT223	96	40	0
DS1267	A1	AUG '99	24347	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	96	34	0
DS1267	A1	FEB '99	24135	9823	ATP (Anam, PI)	DK807766AAH	TSSOP	96	33	0
DS1803	A2	NOV '98	23926	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	96	40	0
DS1803	A2	FEB '99	24006	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	96	36	1
DS1803	A2	AUG '99	24374	9909	ATP (Anam, PI)	DK830515AAB	SOIC	96	36	0
DS1803	A2	NOV '99	24742	9923	ATP (Anam, PI)	DK913631AAA	SOIC	96	40	0
DS2108	B7	AUG '99	24390	9922	ATP (Anam, PI)	DK913650AAF	SOIC	96	40	0
DS2108	B7	FEB '00	25110	9951	ASI (Anam, K)	DK940069AAC	SOIC	96	35	0
DS2109	A7	MAR '99	23835	9839	Carsem	DM812688AA	SOIC	96	31	4
DS2118M	A4	MAR '99	23603	9904	ASI (Anam, K)	DN844402AAC	SSOP	96	40	0
DS2118M	A4	JUN '99	24073	9912	ASI (Anam, K)	DN848138AAA	SSOP	96	40	0
DS2118M	A4	SEP '99	24457	9919	Carsem	DM905555AA	SSOP	96	37	0
DS2165	B1	OCT '98	23171	9837	ASI (Anam, K)	DN811583AAB	LCC	96	38	0
DS2180	B3	APR '99	23882	9850	ASI (Anam, K)	DN839402AAC	LCC	96	37	0
DS21S07A	B3	FEB '99	24213	9851	ATP (Anam, PI)	DK821542AAF	TSSOP	96	26	0
DS21S07A	F	NOV '99	24734	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	96	40	0
DS21S07A	F	AUG '99	24382	9913	Carsem S	DM828145AA	TSSOP	96	40	0
DS2502	C2	APR '99	24267	9845	Carsem	DM821484AA	TSOC	96	69	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2401	C2	DEC '99	24817	9943 Carsem	DM920572AA	TO92	96	40	0
DS2434	D1	NOV '99	24716	9851 Carsem	DM833262AA	TO226 (PR35)	96	40	0
DS2502	C3	JAN '00	25053	9930 CPS (ChipPac, China)	DH917304BAA	TSOC	96	64	0
DS80C320	C5	OCT '99	24588	9938 CPS (ChipPac, China)	DH925592AAB	DIP	96	37	1